High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

FEATURES

- Package type: surface-mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.8
- Peak wavelength: λ_p = 850 nm
- High speed
- Angle of half intensity: φ = ± 60°
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free

e4

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

DESCRIPTION

As part of the SurfLight™ portfolio, the VSMY5850 is an infrared, 850 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, in a low profile 0805 surface mount (SMD) package.

APPLICATIONS

- Miniature light barrier
- Optical switch
- IR point source

PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr) at I_F = 100 mA	φ (°)	λ_p (nm)	t_r (ns)
VSMY5850	13	± 60	850	7

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY5850	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	t_p/T = 0.1, t_p = 100 µs	I_{FM}	200	mA
Surge forward current	t_p = 100 µs	I_{FSM}	500	mA
Power dissipation		P_V	210	mW
Junction temperature		T_j	125	°C
Operating temperature range		T_{amb}	-40 to +110	°C
Storage temperature range		T_{stg}	-40 to +110	°C
Soldering temperature	According to Fig. 7, J-STD-020	T_{sd}	260	°C
Thermal resistance junction-to-ambient	EIA / JESD51	R_{thJA}	280	K/W

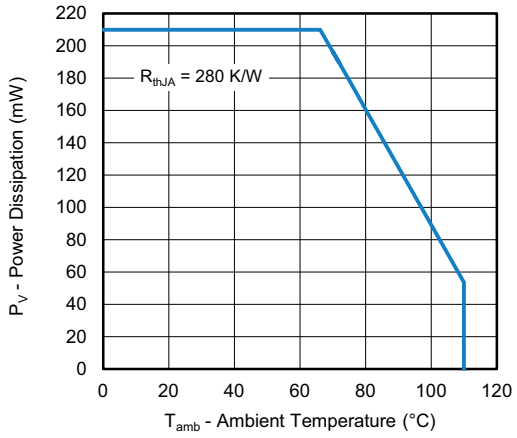


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

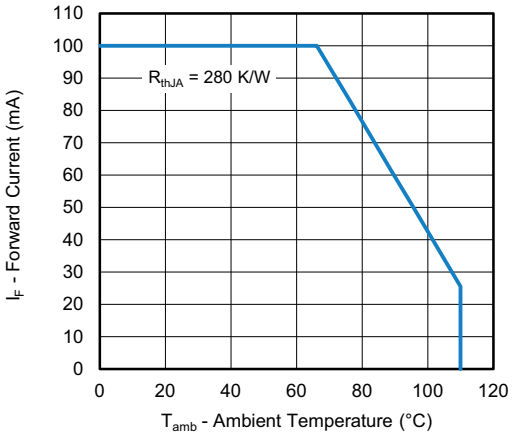


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 100 mA, t_p = 20 ms	V_F	-	1.8	2.1	V
Temperature coefficient of V_F	I_F = 100 mA, t_p = 20 ms	TK_{VF}	-	-1.8	-	mV/K
Reverse current		I_R	Not designed for reverse operation			µA
Junction capacitance	V_R = 0 V, f = 1 MHz, E = 0 mW/cm²	C_J	-	30	-	pF
Radiant intensity	I_F = 100 mA, t_p = 20 ms	I_e	9	13	18	mW/sr
Temperature coefficient of radiant power	I_F = 100 mA, t_p = 20 ms	$TK\phi_e$	-	-0.16	-	%/K
Angle of half intensity		φ	-	± 60	-	°
Peak wavelength	I_F = 100 mA, t_p = 20 ms	λ_p	-	850	-	nm
Spectral bandwidth	I_F = 100 mA, t_p = 20 ms	$\Delta\lambda$	-	35	-	nm
Temperature coefficient of λ_p	I_F = 100 mA, t_p = 20 ms	$TK_{\lambda p}$	-	0.25	-	nm/K
Rise time	I_F = 100 mA, 10 % to 90 %	t_r	-	7	-	ns
Fall time	I_F = 100 mA, 10 % to 90 %	t_f	-	7	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

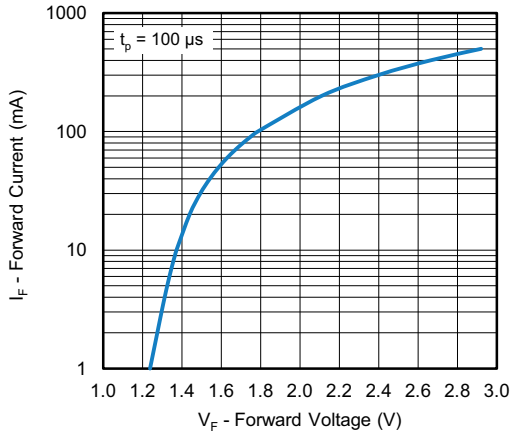


Fig. 3 - Forward Current vs. Forward Voltage

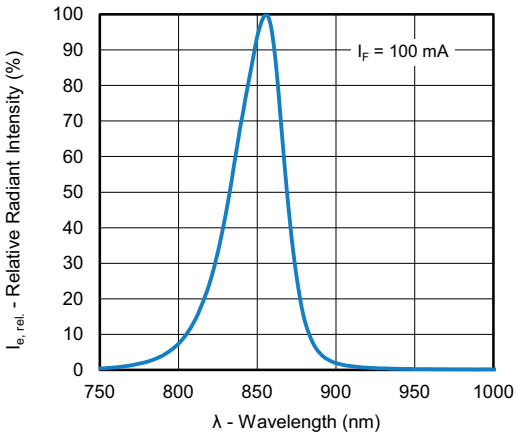


Fig. 5 - Relative Radiant Power vs. Wavelength

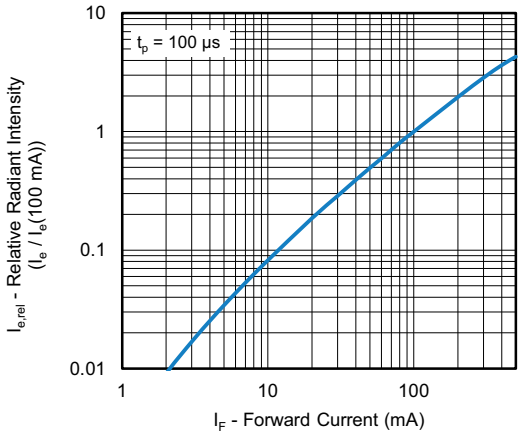


Fig. 4 - Relative Radiant Intensity vs. Forward Current

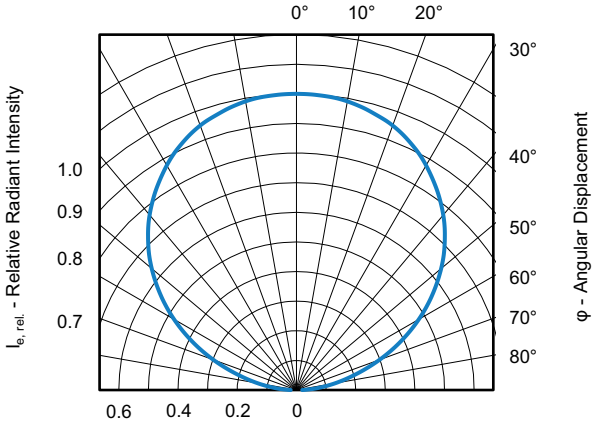


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

REFLOW SOLDER PROFILE

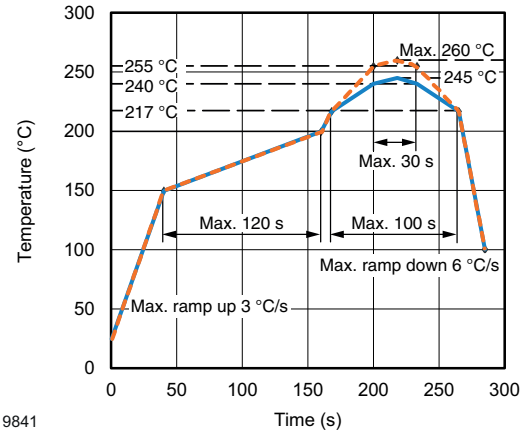


Fig. 7 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

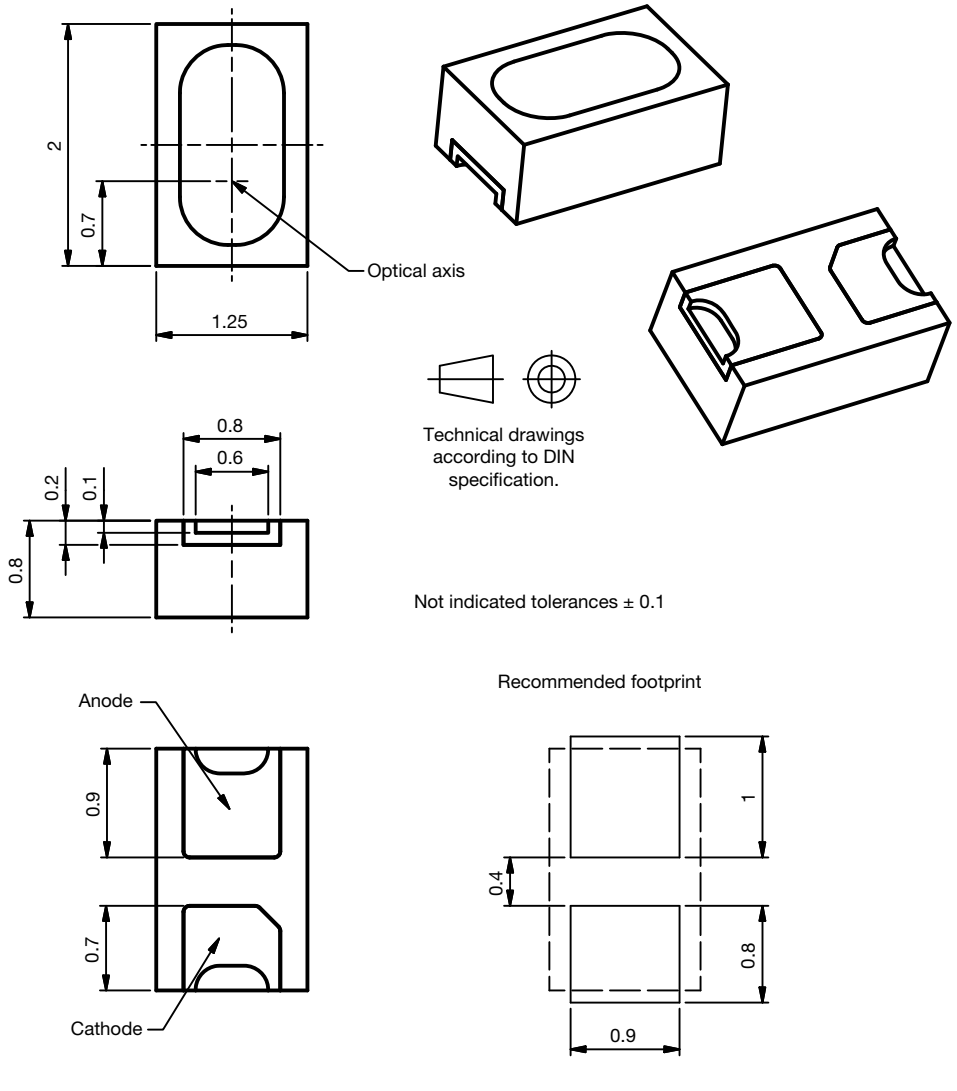
FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:
Moisture sensitivity: level 3
Floor life: 168 h
Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

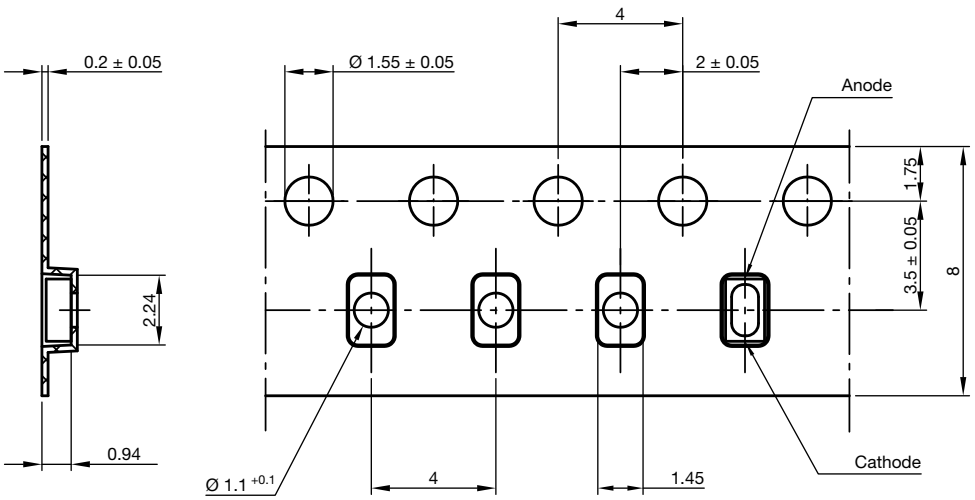
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENSIONS in millimeters



Drawing- No.: 6.550-5352.01-4
Issue: 1; 20.12.2016

BLISTER TAPE DIMENSIONS in millimeters

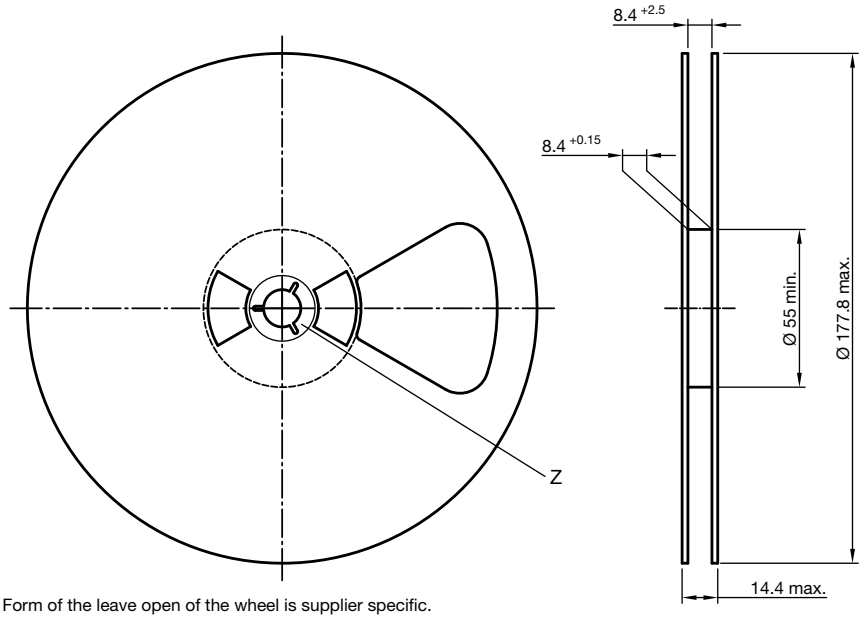


Not indicated tolerances ± 0.1

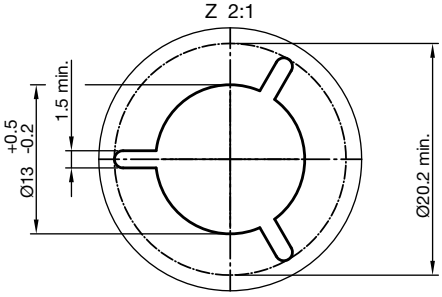
Technical drawings according to DIN specification.

Drawing-No.: 9.700-5352.02-4
Issue: 1; 20.12.2016

REEL DIMENSIONS in millimeters



Form of the leave open of the wheel is supplier specific.



Technical drawings according to DIN specification.

Drawing-No.: 9.800-5096.01-4
Issue: 5; 20.12.2016

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